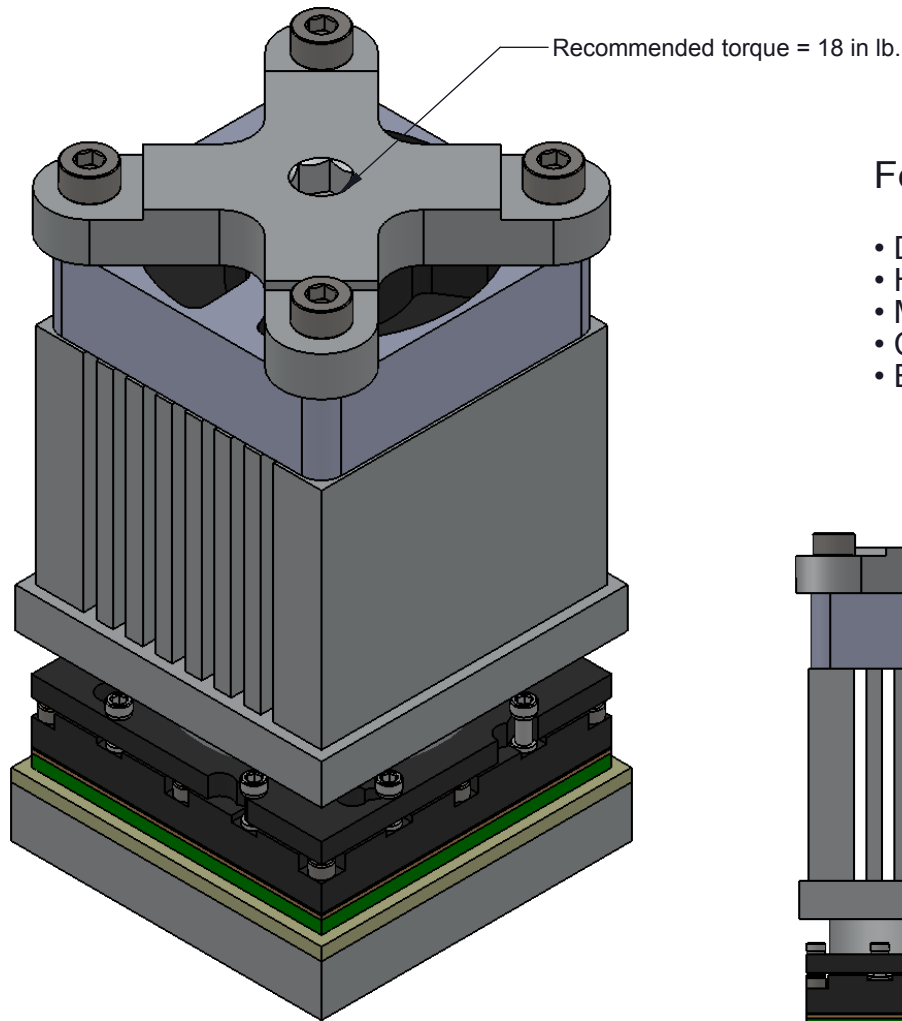
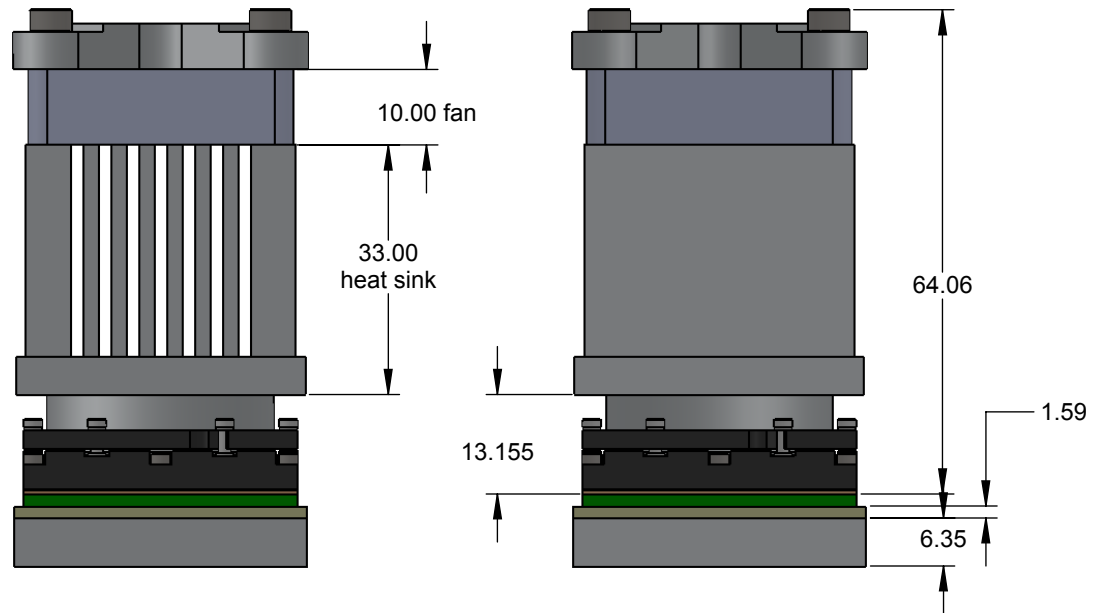


GHz BGA DIRECT MOUNT, SOLDERLESS SOCKET with a Heatsink.



Features

- Directly mounts to target PCB (needs tooling holes) with hardware
- High speed reliable elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Easily removable swivel socket lid



Description: GHz BGA socket with heatsink for 31x31mm 30x30 1mm pitch BGA

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters $\pm 0.03\text{mm}$ [$\pm 0.001''$], Pitches (from true position) $\pm 0.025\text{mm}$ [$\pm 0.001''$], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.13\text{mm}$ [$\pm 0.005''$] unless stated otherwise. Materials and specifications are subject to change without notice.

SG-BGA-8033 Drawing



Ironwood Electronics, Inc.
Tele: (800) 404-0204
www.ironwoodelectronics.com

Material: N/A
Finish: N/A
Weight: 187.47

STATUS: Released

ENG: E. Smolentseva

FILE: SG-BGA-8033 Dwg

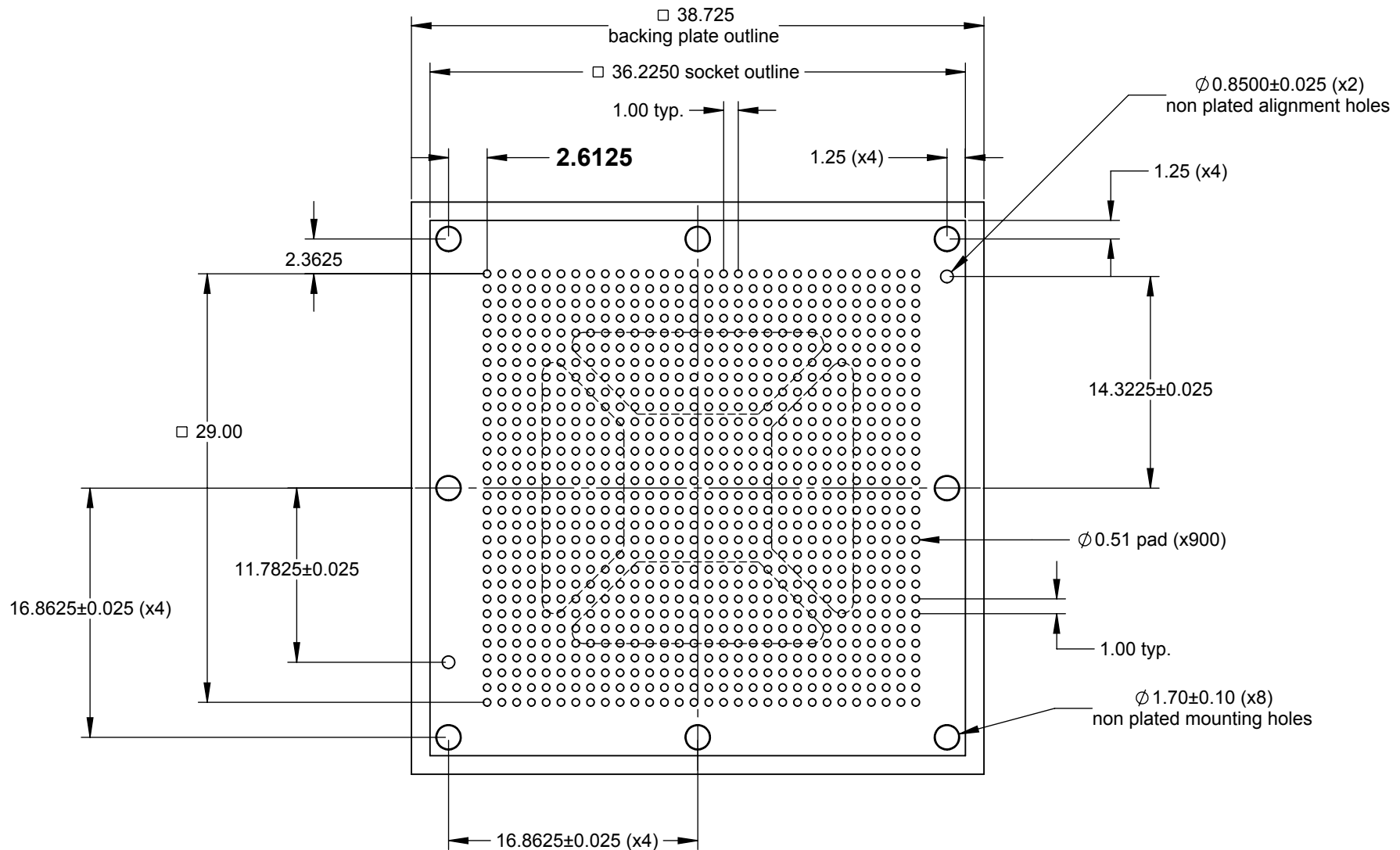
SHEET: 1 OF 5

DRAWN BY: E. Smolentseva

DATE: 12/18/2012

REV. A

SCALE: 1:1




Note: Full BGA pattern shown.
Please adjust pattern according
to individual requirements.

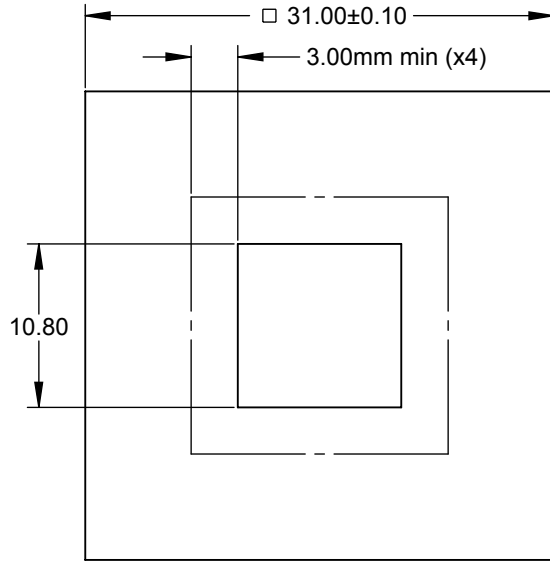
Target PCB Recommendations
Total Thickness: 2.4mm min.
Plating: Gold or Solder finish.
PCB Pad Height: Same or higher than solder mask.

Description: Recommended PCB layout

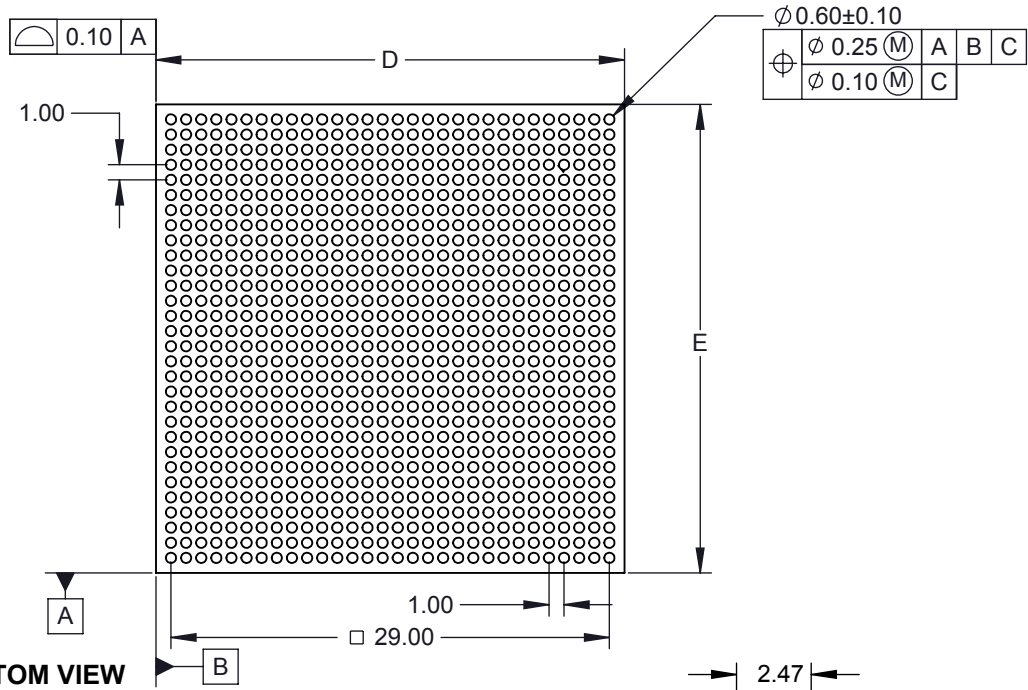
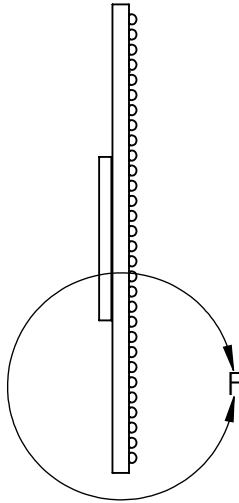
Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.
 Tolerances: Hole diameters $\pm 0.03\text{mm}$ [$\pm 0.001''$], Pitches (from true position) $\pm 0.025\text{mm}$ [$\pm 0.001''$], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.13\text{mm}$ [$\pm 0.005''$] unless stated otherwise. Materials and specifications are subject to change without notice.

 SG-BGA-8033 Drawing Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: N/A Finish: N/A Weight: 187.47	STATUS: Released	SHEET: 2 OF 5	REV. A
		ENG: E. Smolentseva	DRAWN BY: E. Smolentseva	SCALE: 2.5:1
		FILE: SG-BGA-8033 Dwg	DATE: 12/18/2012	

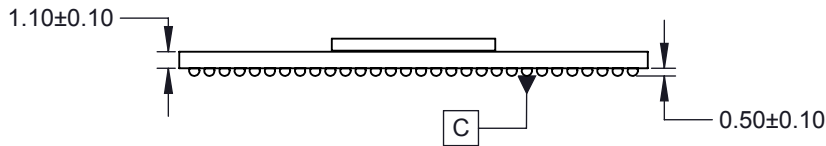
Ironwood Package Code: BGA900A



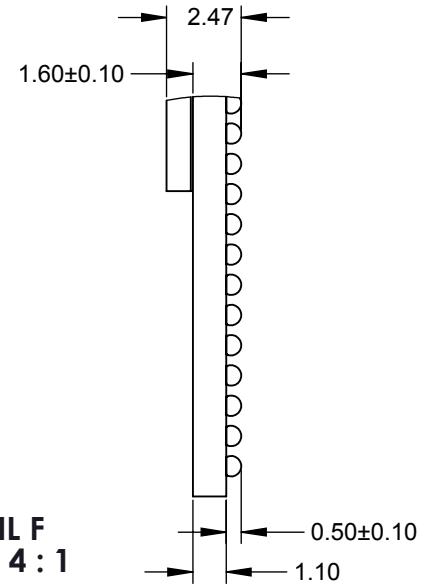
TOP VIEW



BOTTOM VIEW



SIDE VIEW




**DETAIL F
SCALE 4 : 1**

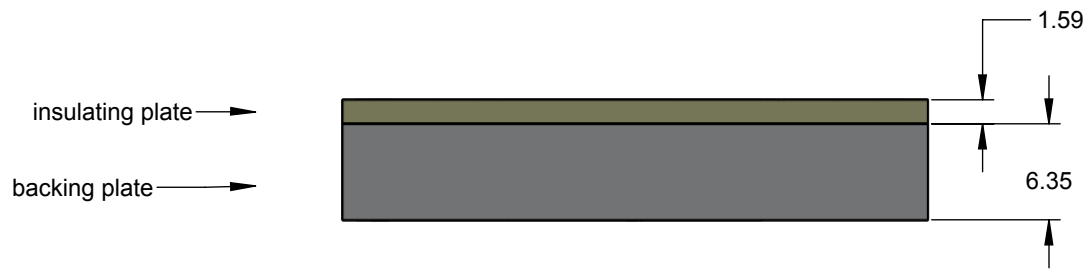
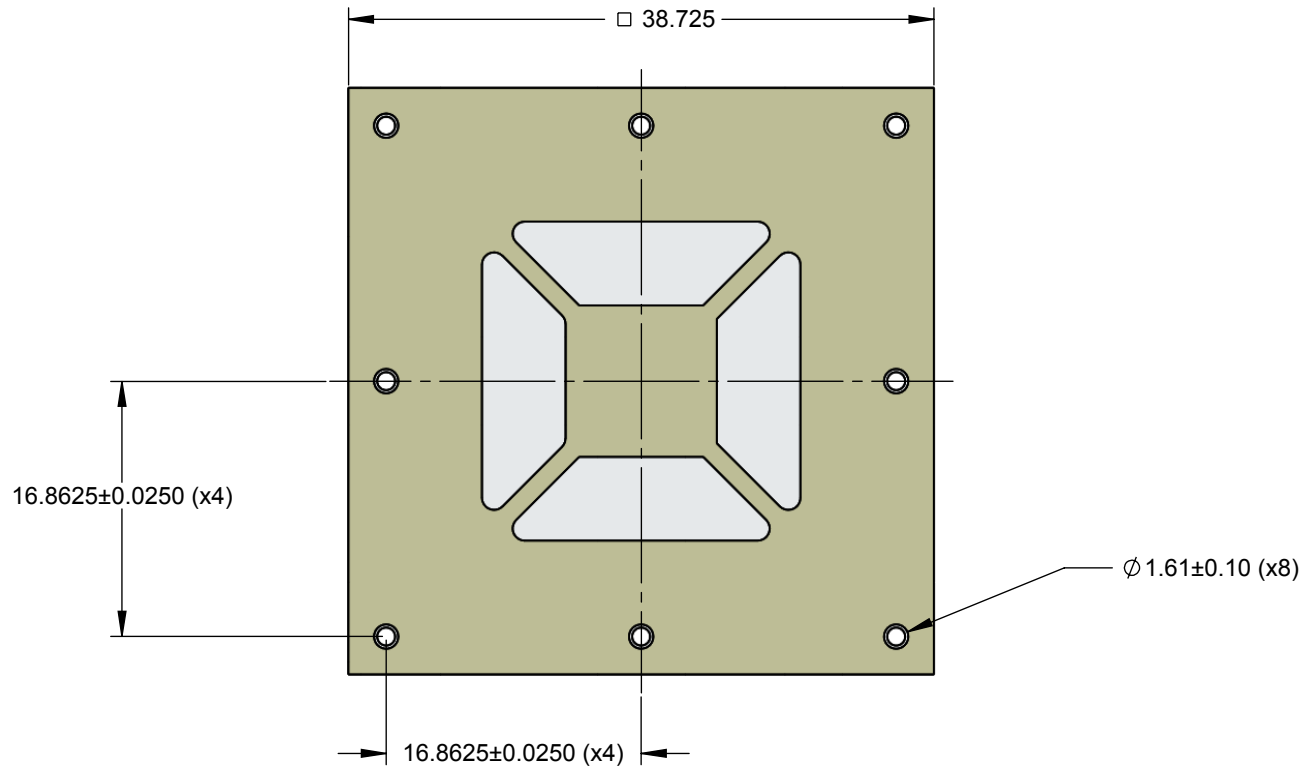
1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane C.
4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
5. Parallelism measurement shall exclude any effect of mark on top surface of package.

Description: Compatible BGA device

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters $\pm 0.03\text{mm}$ [$\pm 0.001''$], Pitches (from true position) $\pm 0.025\text{mm}$ [$\pm 0.001''$], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.13\text{mm}$ [$\pm 0.005''$] unless stated otherwise. Materials and specifications are subject to change without notice.


 SG-BGA-8033 Drawing Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: N/A Finish: N/A Weight: 187.47	STATUS: Released ENG: E. Smolentseva FILE: SG-BGA-8033 Dwg	SHEET: 3 OF 5 DRAWN BY: E. Smolentseva DATE: 12/18/2012	REV. A SCALE: 2:1

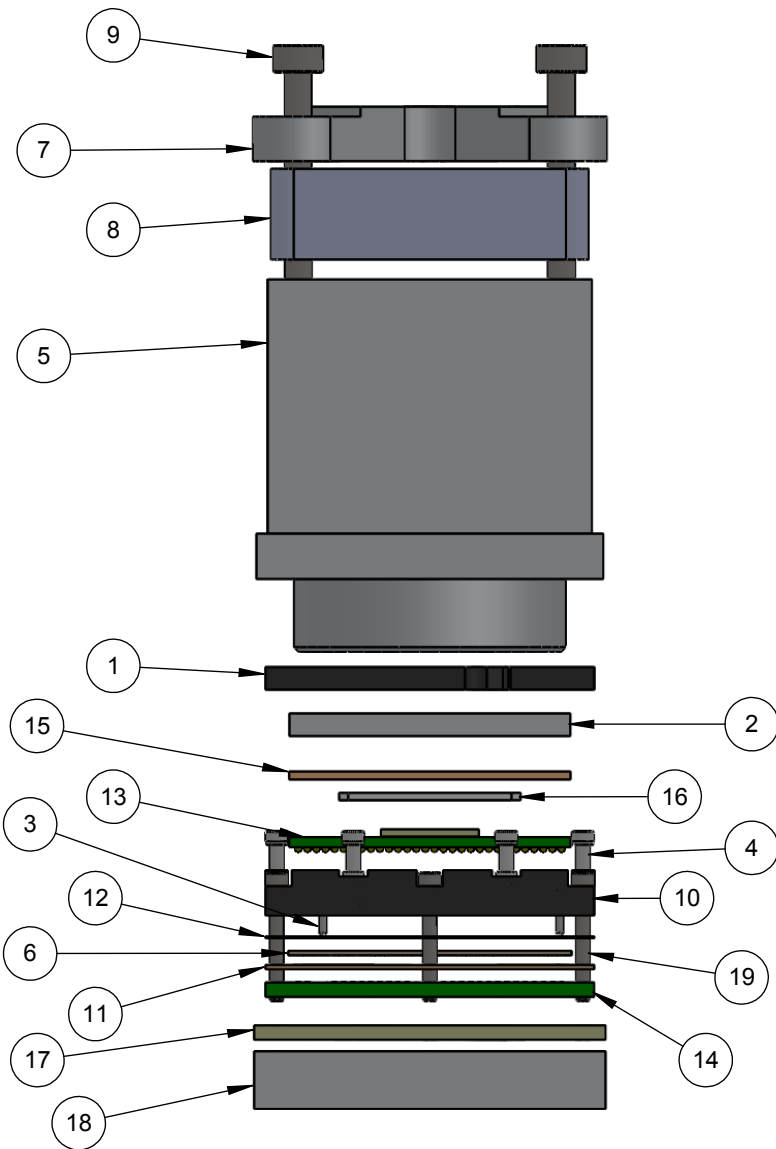


Description: Backing and Insulating Plate

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

 SG-BGA-8033 Drawing Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: N/A Finish: N/A Weight: 187.47	STATUS: Released	SHEET: 4 OF 5	REV. A
		ENG: E. Smolentseva	DRAWN BY: E. Smolentseva	SCALE: 2:1
		FILE: SG-BGA-8033 Dwg	DATE: 12/18/2012	




ITEM NO.	DESCRIPTION	Material
1	Swivel Socket Lid 31mm IC	7075-T6 Aluminum Alloy
2	Compression Plate	7075-T6 Aluminum Alloy
3	Dowel Pin, 1/32" x 3/16", SS	Chrome Stainless Steel
4	#0-80 Shoulder Screw, 0.090" thread length	Stainless Steel (303)
5	Heat Sink Lid	7075-T6 Aluminum Alloy
6	0.5mm thick 0.1mm pitch 63 deg angled elastomer	Silicon Rubber
7	Torquing bracket	7075-T6 Aluminum Alloy
8	Fan: 35MMX35MMX10MM 12V 6.5CFM	Material <not specified>
9	Screw, M3 x 0.5mm, 25mm lg, Low Head Cap, SS	Stainless Steel (18-8)
10	Socket Base	7075-T6 Aluminum Alloy
11	Elastomer Guide 31mm IC	Ultem 1000
12	Ball Guide	Kapton Polyimide/Cirlex
13	Customer's BGA IC	FR4 Standard
14	Target PCB 30x30 array 1mm	Material <not specified>
15	IC Frame for 31mm IC	Ultem 1000
16	Gap pad 19.2mm Square cut to size	Gap Pad A3000
17	Insulation Plate	High Temp FR4
18	Backing Plate	7075-T6 Aluminum Alloy
19	#0-80 x 0.5, SH Cap Screw	Alloy Steel

Rev	Date	Initials	Description
A	12/18/12	ELS	Original

Description: Material info

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters $\pm 0.03\text{mm}$ [$\pm 0.001"$], Pitches (from true position) $\pm 0.025\text{mm}$ [$\pm 0.001"$], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.13\text{mm}$ [$\pm 0.005"$] unless stated otherwise. Materials and specifications are subject to change without notice.

 SG-BGA-8033 Drawing Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: N/A Finish: N/A Weight: 187.47	STATUS: Released	SHEET: 5 OF 5	REV. A
		ENG: E. Smolentseva	DRAWN BY: E. Smolentseva	SCALE: 1.2:1
		FILE: SG-BGA-8033 Dwg	DATE: 12/18/2012	